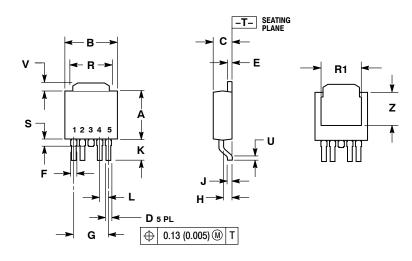
ONSEMI



SCALE 1:1

DPAK-5, CENTER LEAD CROP CASE 175AA ISSUE B

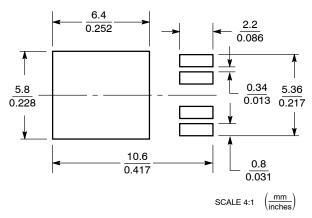
DATE 15 MAY 2014



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

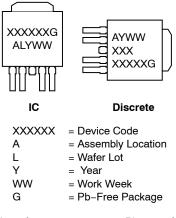
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.22	
в	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.020	0.028	0.51	0.71	
Е	0.018	0.023	0.46	0.58	
F	0.024	0.032	0.61	0.81	
G	0.180 BSC		4.56 BSC		
н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
К	0.102	0.114	2.60	2.89	
L	0.045	0.045 BSC		1.14 BSC	
R	0.170	0.190	4.32	4.83	
R1	0.185	0.210	4.70	5.33	
S	0.025	0.040	0.63	1.01	
U	0.020		0.51		
V	0.035	0.050	0.89	1.27	
Z	0.155	0.170	3.93	4.32	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, <u>SOLDERRM/D</u>.

GENERIC MARKING DIAGRAMS*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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DESCRIPTION:	DPAK-5 CENTER LEAD C	PAK-5 CENTER LEAD CROP				
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